

Title (en)

Heat sink module for electronic semiconductor devices

Title (de)

Wärmesenkenmodul für elektronische Halbleitervorrichtungen

Title (fr)

Module de dissipateur pour dispositifs de semi-conducteurs électroniques

Publication

EP 2458632 B1 20130731 (EN)

Application

EP 10425359 A 20101124

Priority

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Abstract (en)

[origin: EP2458632A1] The invention relates to a heat sink module (100) for electronic semiconductor devices (40). Such module comprises: - a dissipating body (10) with fins (2) that operates for removing the heat developed by said electronic devices (40), - means (20, 30, 50, 60) for housing and fixing said electronic semiconductor devices (40) to the dissipating body (10). The module is characterised in that said housing and fixing means (30, 50, 60) comprise a frame (30) removably fixed to the dissipating body (10) for defining at least two independent slots (33) with said body for housing the electronic devices. Each of said at least two slots is occupied by a single electronic device removable from the slot.

IPC 8 full level

H01L 23/40 (2006.01)

CPC (source: EP)

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Cited by

DE102019206523A1; CN113555190A; DE102019218157A1; EP3208843A1; DE102016123113B3; CN109119391A; JP2016129213A; US11652021B2; DE102023110340B3; WO2024012807A1

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